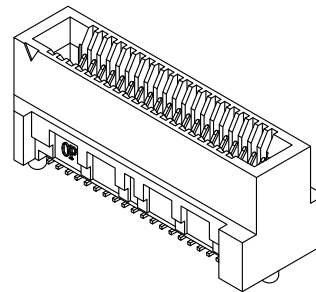
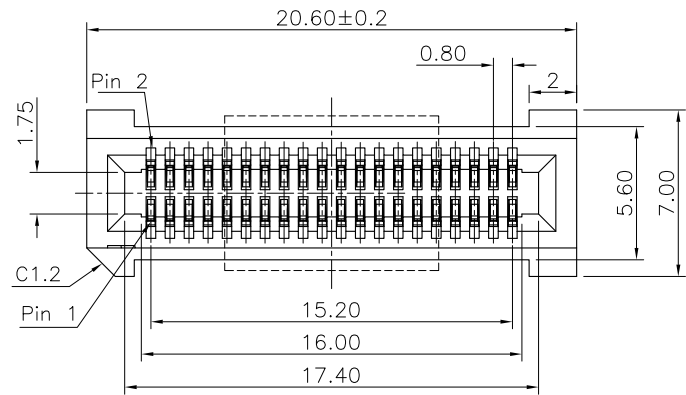


REV.	SPECIFICATION	ECN NO.	APPD.
R8		ECN211220	



**Material and Plating :**

**Housing:** LCP,UL94V-0,BLACK.

**Contacts:** High performance Copper Alloy

Gold Plated on Contact Area and 80u" Min Tin Plated on solder tail over Nickel 50u" Min.

**Electrical Characteristics:**

**Current Rating:** 3.1 AMP.

**Dielectric Withstanding Voltage:** AC 600V For 1 minute.

**Insulator Resistance:** 6000MΩ min. at DC 250V.

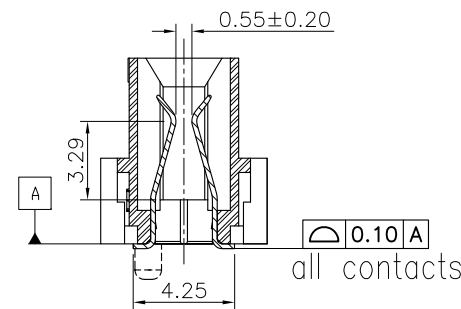
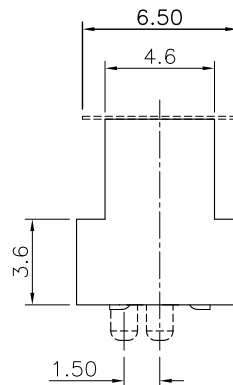
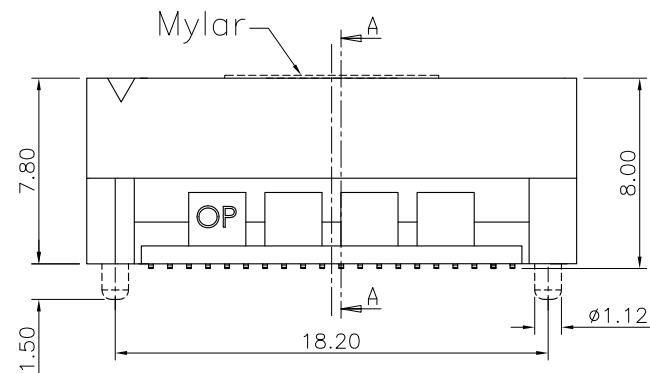
**Contact Resistance:** 8.4mΩ max. at DC 100mA.

**Operating Temperature:** -55°C~+125°C.

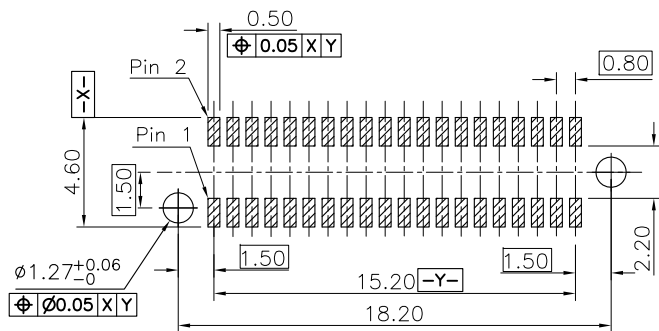
**\*RoHS Compliant**

**Insertion Depth:** 3.15mm To 5.55mm.

**Speed:**28+Gbps @-3dB.



Section A-A



P.C. Board Layout  
(Tolerance ±0.05)

Series **8206- 2 X 20 C xx D P x - x**

- S: Mylar
- P: Plastic Pad
- Blank: Without Pad , Without Mylar
- T: Tape&Reel Packaging
- U: Tube Packaging
- A: Tray Packaging
- P: With Post
- N: Without Post
- D: SMD Type

Position Per Row

- C: Selective Gold Plated

10: 10u"  
30: 30u"

Tolerances	Dwg.No.	8206-D0000-007		Title:	
x = ±0.50	Projection			8206 Series Edge Card Connector 0.80mm (0.0315") Pitch SMD Type	
.x = ±0.25	Unit	mm	Scale		1:1
.xx = ±0.15	Drawn By	ZY 12/22'21			

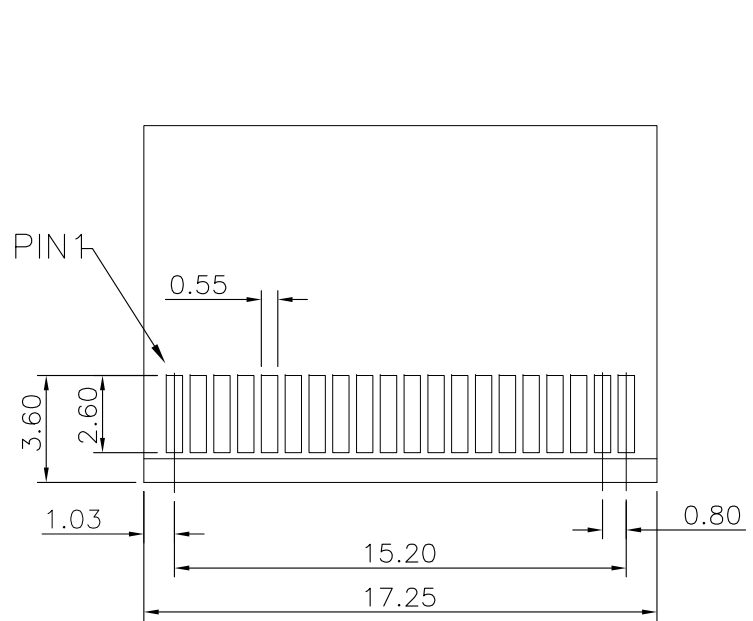


OUPIN ELECTRONIC(KUNSHAN) CO., LTD.

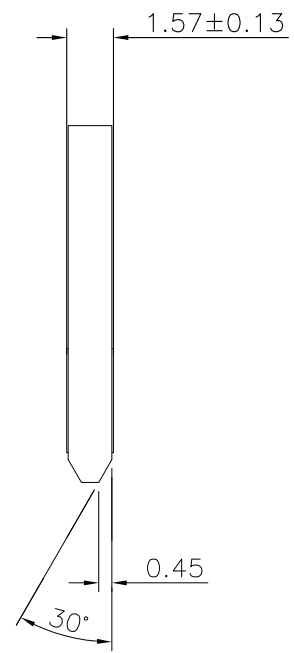
P/N: 8206-2X20CxxDPx-x



SHEET	1/2	Ver.No.	R8
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REV.	SPECIFICATION	ECN NO.	APPD.
R8		ECN211220	



**RECOMMENDED MATTING BOARD FOOTPRINT**  
(Tolerance: ±0.05)



<b>Tolerances</b> x = ±0.50 .x = ±0.25 .xx = ±0.15	<b>Dwg.No.</b> 8206-D0000-007		<b>Title:</b>		 <b>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</b>
	<b>Projection</b> 		8206 Series Edge Card Connector		
	<b>Unit</b> mm	<b>Scale</b> 1:1	0.80mm (0.0315") Pitch SMD Type		<b>SHEET</b> 2/2 <b>Ver.No.</b> R8
	<b>Drawn By</b> ZY 12/22'21				